

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20190111000.0.A Datasheet for AM3352 Information Only

Correction: Rev A is being issued to include additional affected devices.

Date: February 12, 2019

To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
AM3352BZCZD80	null
AM3357BZCZD60	null
AM3352BZCZ100	null
AM3356BZCZA80	null
AM3357BZCZA80	null
AM3357BZCZD30	null
AM3352BZCZA100	null
AM3352BZCZD60	null
AM3352BZCZ60	null
AM3354BZCZD80	null
AM3354BZCZA80	null
AM3358BZCZA100	null
AM3352BZCZ80	null
AM3352BZCZ30	null
AM3352BZCZA80	null
AM3352BZCZA60	null
AM3354BZCZA100	null
AM3357BZCZA60	null
AM3359BZCZA80	null
AM3352BZCZD30	null
AM3351BZCE30	null

Technical details of this Product Change follow on the next page(s).

PCN Number: 201901110		000	D.O.A PCN Date: F		Fe	Feb. 12, 2019				
Title:	Title: Datasheet for AM3352									
Custon	ner Contact:	PCN Manage			<u>er</u>			Dept:		Quality Services
Change Type:										
Ass	sembly Site				Design				Wafer	Bump Site
Assembly Process		□ Data Sheet				Wafer	Bump Material			
Ass	Assembly Materials		Part number change				Wafer	Bump Process		
Me	chanical Specifi	ication			Test Site				Wafer	Fab Site
Pac	king/Shipping/	'Labeli	ng		Test Proce	ess			Wafer	Fab Materials
									Wafer	Fab Process
Notification Details										
Description of Change:										
Texas Instruments Incorporated is appounding an information only notification										

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.

Correction: Rev A is being issued to include additional affected devices.



AM3359, AM3358, AM3357, AM3356, AM3354, AM3352, AM3351

SPRS717K - OCTOBER 2011-REVISED DECEMBER 2018

Chang	jes from April 1, 2016 to i	December 15, 2018 (from J Re	evision	(April 2016) to K Revision	1) Pa	age		
•		DRD (Dual-Role Device)						
•	Removed OpenVG 1.0							
•	Updated Description text							
•		to "DRD"						
•	Removed 600 MHz from Frequency and 1200 from MIPS for AM3359							
•	Added DEV_FEATURE register value to Device Comparison							
•	Added 125°C Latch-up pe	Added 125°C Latch-up performance info						
•	Updated DDR3/DDR3L maximum frequency for industrial extended temperature							
•	Added Industrial Extended operating temperature range							
•	Updated/Changed footnote for Output Capacitor Characteristics from "RTC_KLDO_ENn" to "RTC_KALDO_ENn" 94							
	Added ADC clock frequency to TSC_ADC Electrical Parameters							
	Added new footnotes 99 Added DCAN Timing Conditions 116							
	Added DMTimer Timing Conditions 117 Added DMTimer Timing Conditions 117							
		time, MDC						
		cteristics for MDIO_DATA						
		witching Characteristics for RMI						
		RD and Transition time, RX_C						
		MII Mode				124		
•								
•	 Removed Transition time, TD and Transition time, TX_CTL from Switching Characteristics for RGMII[x]_TD[3:0], 							
(2.7	and RGMII[x]_TCTL - RGMII Mode 125							
:	Removed content from GPMC and NOR Flash Switching Characteristics—Synchronous Mode							
	Produced 110. 1 11 Yellows							
	Swapped F22 and F21 in GPMC and NOR Flash—Synchronous Burst Read—4x16-Bit (GpmcFCLKDivider = 0) . 132							
	Removed content from GPMC and NOR Flash Switching Characteristics—Asynchronous Mode 136 Removed content from GPMC and NAND Flash Switching Characteristics—Asynchronous Mode 145							
	Removed content from GPMC and NAND Flash Switching Characteristics—Asynchronous Mode							
	Removed Rise time and Fall time info from Switching Characteristics for I ² C Output Timings							
	Added JTAG Timing Conditions 191 Added content to LCD Controller Timing Conditions 192							
	Removed content for Switching Characteristics for LCD LIDD Mode 193							
		witching Characteristics for McS						
		witching Characteristics for MM						
		RU-ICSS PRU Switching Requi						
		RU-ICSS PRU Switching Requi						
		RU-ICSS ECAT Switching Requ						
	Removed transition time,	MDC from PRU-ICSS MDIO SV	witching	Characteristics - MDIO_CL	K 2	227		
		Switching Characteristics - M				228		
•	Updated Note in PRU-ICS	SS MII_RT Electrical Data and	Timing.		2	228		
•	Added UART Timing Con	ditions			2	230		
•	Added UART Timing Con							
•	Added Carrier Type to Figure 8-1, AM335x Device Nomenclature							
The o	datasheet number wil	I be changing.						
De	vice Family			Change From:	Change To:			
A B 4	2252			SPRS717J	SPRS717K			
	3352		L 1: 1		J1 1(3/1/1)			
ines	se changes may be re	eviewed at the datashee	t iinks	s proviaea.				
<u>http</u>	://www.ti.com/produ	ct/AM3352						
Rea	son for Change:							
	ccurately reflect devi	ce characteristics.						
	•	Fit, Form, Function, Q)ualit	v or Reliability (nos	sitive / negative)			
	anticipated impact. Tr actual device.	nis is a specification cha	nge a	imouncement only. If	iere are no change	:S (0		
		entification resulting	from	this PCN:				
Non	•							
	duct Affected:							
		AM22E2DZCZTC2D						
ΗI	3352BZCZT60	AM3352BZCZT60R	AM3	354BZCZ100	AM3356BZCZA80			

AM3351BZCE30	AM3352BZCED60	AM3354BZCZ30	AM3356BZCZD30
AM3351BZCE30R	AM3352BZCZ100	AM3354BZCZ60	AM3356BZCZD60
AM3351BZCE60	AM3352BZCZ30	AM3354BZCZ80	AM3357BZCZA30
AM3351BZCE60R	AM3352BZCZ60	AM3354BZCZA100	AM3357BZCZA60
AM3351BZCEA30	AM3352BZCZ80	AM3354BZCZA60	AM3357BZCZA80
AM3351BZCEA30R	AM3352BZCZA100	AM3354BZCZA80	AM3357BZCZD30
AM3351BZCEA60	AM3352BZCZA30	AM3354BZCZA80R	AM3357BZCZD60
AM3352BZCE30	AM3352BZCZA60	AM3354BZCZD60	AM3358BZCE60
AM3352BZCE30R	AM3352BZCZA80	AM3354BZCZD80	AM3358BZCZ100
AM3352BZCE60	AM3352BZCZD30	AM3356BZCEA60	AM3358BZCZ60
AM3352BZCEA30	AM3352BZCZD60	AM3356BZCZ30	AM3358BZCZ80
AM3352BZCEA30R	AM3352BZCZD80	AM3356BZCZ60	AM3358BZCZA100
AM3352BZCEA60	AM3354BZCE60	AM3356BZCZ80	AM3358BZCZA80
AM3352BZCEA60R	AM3354BZCEA60	AM3356BZCZA30	AM3359BZCZA80
AM3352BZCED30	AM3354BZCED60	AM3356BZCZA60	

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN www admin_team@list.ti.com